

IPU 18

PATENT APPLICATION

10551/489

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: J. Thomas WALKER

Application No.: 10/625,552

Examiner: DINH, TUAN T

Group Art Unit: 2841

Confirmation No. 8103

Filed: July 24, 2003

For: ATTACHABLE MODULAR ELECTRONIC SYSTEMS

INFORMATION DISCLOSURE STATEMENT

MAIL STOP AMENDMENT

03/11/2005 SDENB0B1 00000142 110600 10625552

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

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Sir:

Pursuant to 37 CFR § 1.56, the attention of the Patent and Trademark Office is hereby directed to the reference(s) listed on the attached PTO-1449. Unless otherwise indicated herein, one copy of each reference is attached. It is respectfully requested that the information be expressly considered during the prosecution of this application, and that the reference(s) be made of record therein and appear among the "References Cited" on any patent to issue therefrom. The filing of this Information Disclosure Statement and the enclosed PTO Form No. 1449, shall not be construed as an admission that the information cited is prior art, or is considered to be material to patentability as defined in 37 C.F.R. § 1.56(b). The paragraphs marked below are applicable. It is believed that no fees other than those indicated below are due, but authorization is hereby given to charge any additional fees due, or to credit any overpayment, to deposit account 11-0600.

■ 1. This Information Disclosure Statement is being filed (a) within three months of the filing date of a national application other than a continued prosecution application under 37 C.F.R. §1.53(d), (b) within three months of the date of entry of the national stage as set forth in 37 C.F.R. § 1.491 in an international application, (c) before the mailing date of a first Office Action on the merits in the present application, OR (d) before the mailing of a first office action after filing of a request for continued examination. No certification or fee is required.

2. This Information Disclosure Statement is being filed more than three months after the U.S. filing date AND after the mailing date of the first Office Action on the merits, but before the mailing date of a final action, Notice of Allowance, or any action that otherwise closes prosecution.

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Applicant: J. Thomas WALKER
Serial No. 10/625,552
IDS filed March 10, 2005

a. I hereby certify that each item of information contained in this Information Disclosure Statement was first cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this Information Disclosure Statement. 37 CFR §1.97(e)(1).

b. I hereby certify that no item of information in this Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to my knowledge after making reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this Information Disclosure Statement. 37 CFR §1.97(e)(2).

c. Please debit Deposit Account No. 11-0600 in the amount of \$180.00 in payment of the fee under 37 CFR §1.17(p) to ensure consideration of the disclosed information. Two duplicate copies of this paper are attached. 37 CFR §1.97(c)(2).

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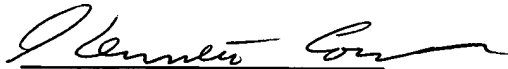
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Respectfully submitted,

KENYON & KENYON

Date: March 10, 2005


Kenneth R. Corsello
Registration No. 38,115

Suite 700
1500 K Street, N.W.
Washington, D.C. 20005
Telephone: (202) 220-4200
Facsimile: (202) 220-4201

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Sheet 1 of 3

Complete if Known

Application Number	10/625,552
Filing Date	July 24, 2003
First Named Inventor	J. Thomas WALKER
Art Unit	2841
Examiner Name	DINH, TUAN T
Attorney Docket Number	10551/489

U.S. PATENT DOCUMENTS

Examiner Initials *	Cite No. ¹	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number - Kind Code ² (if known)			
		US-6,297,564 B1	10-02-2001	Chung	
		US- 6,297,559 B1	10-02-2001	Call et al.	
		US- 6,184,053 B1	02-06-2001	Eldridge et al.	
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		US- 4,701,279	10-20-1987	Kawaguchi et al.	

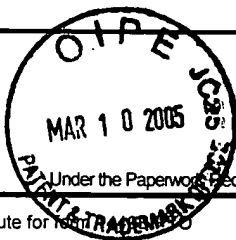
FOREIGN PATENT DOCUMENTS

Examiner Initials *	Cite No. ¹	Foreign Patent Document	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T ⁶
		Country Code ³ - Number ⁴ - Kind Code ⁵ (if known)				
		EP 0 948 813 B1	10-09-1997	Hans-Hermann Oppermann et al.		
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		JP 03-246773	12/03/1993	Techno Sunstar		

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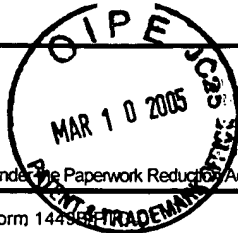
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NON PATENT LITERATURE DOCUMENTS

Examiner Initials *	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
		"Theoretical and Experimental Aspects in the Depositing Process of Solder and Adhesive Pates in Surface Mount Technology," Alexandru Marin et al., IEEE Polytronic 2002 Conference, pp. 150-154.	
		"Isotropically Conductive Adhesives for High Power Electronics Applications," Kristian Olsson et al., IEEE Polytronic 2002 Conference, pp. 29-37.	
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		"Electroconductive Adhesives to Grow into Major Market," <u>Japan Chemical Week</u> , January 16, 2003, p. 3.	
		"U.S. Demand for Electronic Polymer Products to Expand 6.4% Annually Through 2005," Adhesives & Sealants Industry, Vol. 9, Number 4, May 2002, p. 26.	

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**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

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Sheet 3 Of 3

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Examiner Initials *	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
		"Lead-Free Pastes Fail to Stick," <u>Adhesives Age</u> , Vol. 44, No. 9, September 2001, p. 9.	
		"Using Conductive Adhesives for Grounding Applications," Stanley Tead et al., 23rd-24th October 2000, Paper 115, Conference Paper, Charlotte, NC.	
		"More Secure Bonding for Fine Pitch Surface Mount Device Structural Elements," (English translation), by Thomas Gesang et al., <u>Adhasion Kleben & Dichten</u> , pp. 27-32, Nos. 7-8, 1998.	
		"Niche Applications Lift the Adhesives and Sealants Market," <u>Chemical Market Reporter</u> , May 21, 2001, Vol. 259, No. 21.	
		Jarmo Määttänen et al., "Development of Fine Pitch (54 µm) Flip Chip on Flex Interconnection Process," <i>IEEE Polytronic 2002 Conference</i> , pp. 155-159, 2002.	
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		Carl Yallop, "Conductive adhesives provide solution to electronic assembly problems," <i>European Design Engineer</i> , October 2001, pp. 50-51.	

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